"Layout and Use of Bond Pads and Probe Pads for Testing of Integrated Circuits Devices" Inventor: Adrian E. Ong Atty. Docket No.: 24295-81051 Sheet 1 of 9

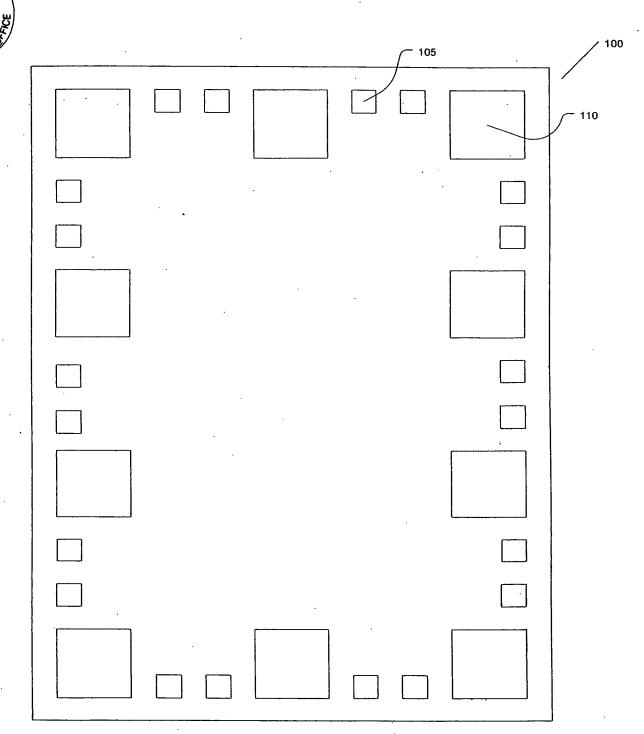


FIG. 1

"Layout and Use of Bond Pads and Probe Pads for Testing of Integrated Circuits Devices" Inventor: Adrian E. Ong Atty. Docket No.: 24295-81051 Sheet 2 of 9

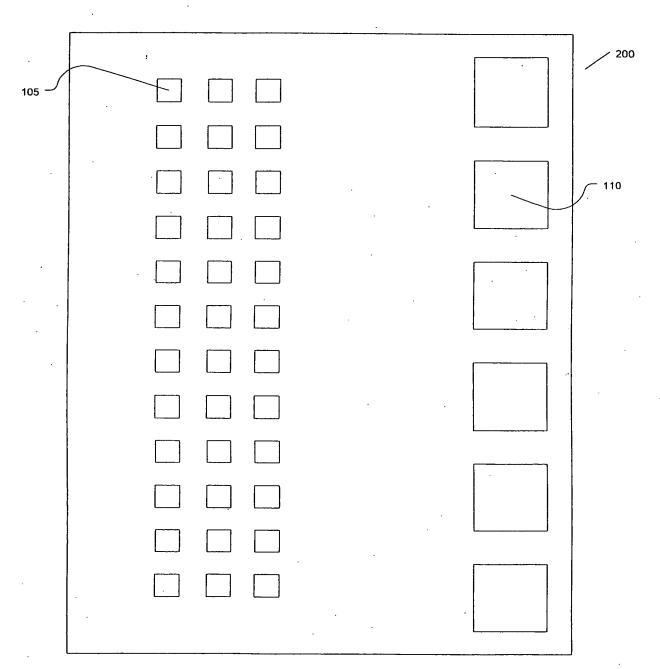


FIG. 2

"Layout and Use of Bond Pads and Probe Pads for Testing of Integrated Circuits Devices" Inventor: Adrian E. Ong Atty. Docket No.: 24295-81051 Sheet 3 of 9

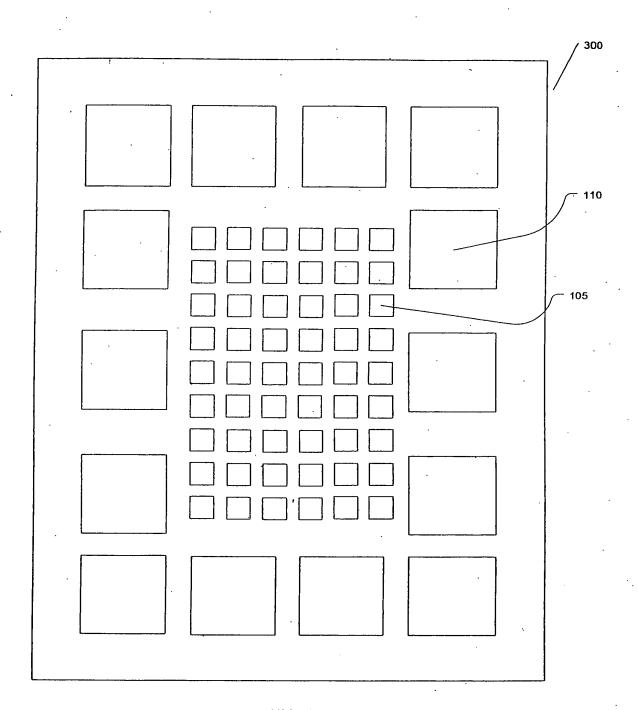


FIG. 3

"Layout and Use of Bond Pads and Probe Pads for Testing of Integrated Circuits Devices" Inventor: Adrian E. Ong Atty. Docket No.: 24295-81051 Sheet 4 of 9

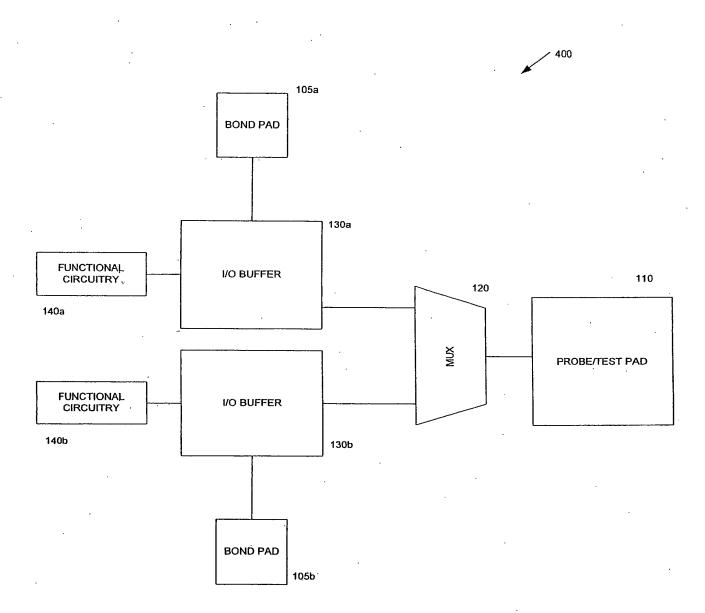


FIG. 4

"Layout and Use of Bond Pads and Probe Pads for Testing of Integrated Circuits Devices" Inventor: Adrian E. Ong Atty. Docket No.: 24295-81051 Sheet 5 of 9

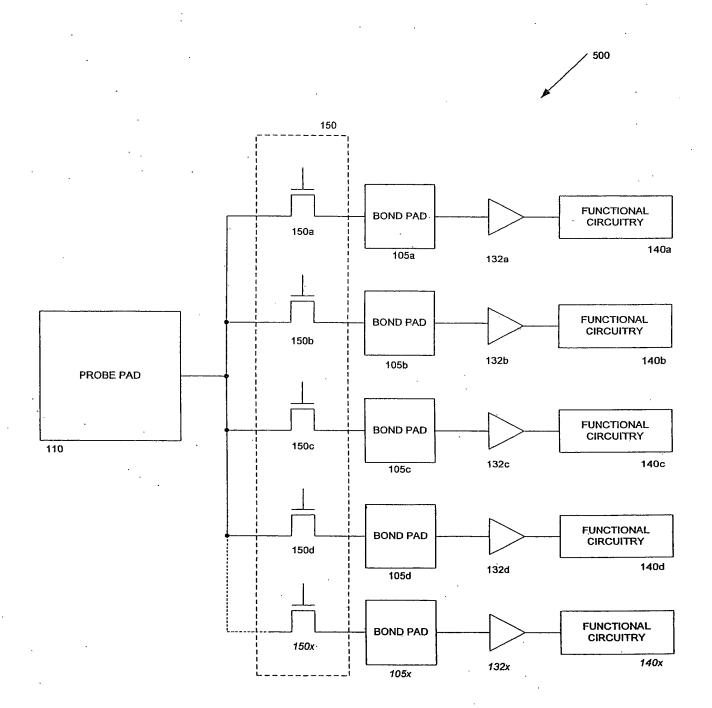


FIG. 5

"Layout and Use of Bond Pads and Probe Pads for Testing of Integrated Circuits Devices" Inventor: Adrian E. Ong Atty. Docket No.: 24295-81051 Sheet 6 of 9



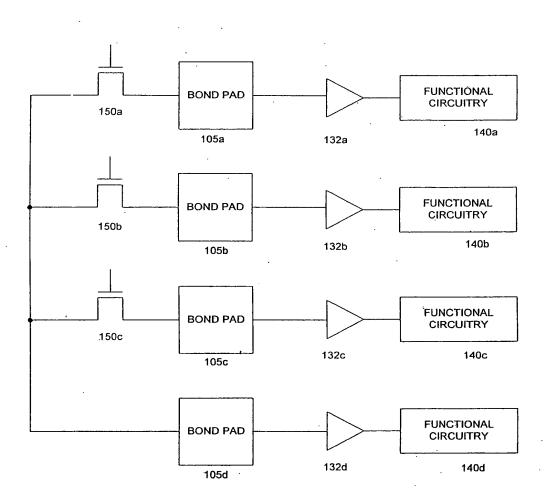


FIG. 6

"Layout and Use of Bond Pads and Probe Pads for Testing of Integrated Circuits Devices" Inventor: Adrian E. Ong Atty. Docket No.: 24295-81051 Sheet 7 of 9

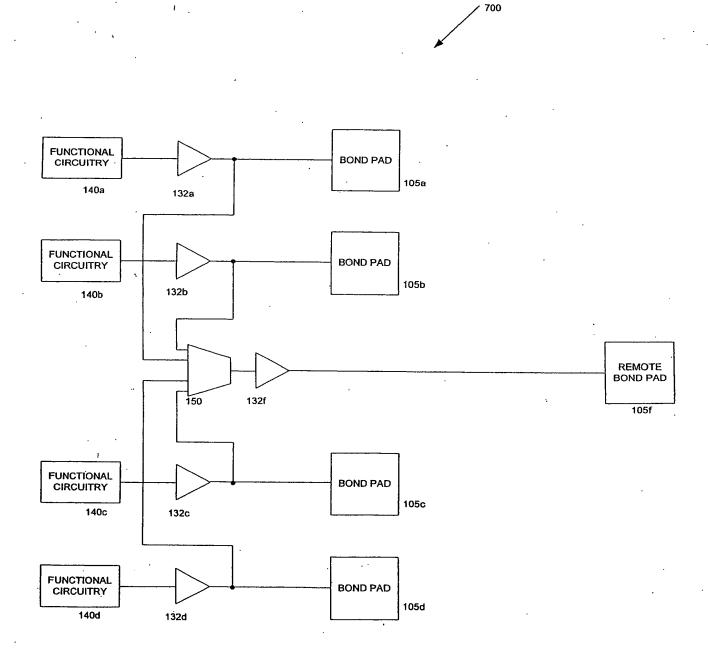


FIG. 7

"Layout and Use of Bond Pads and Probe Pads for Testing of Integrated Circuits Devices" Inventor: Adrian E. Ong Atty. Docket No.: 24295-81051 Sheet 8 of 9

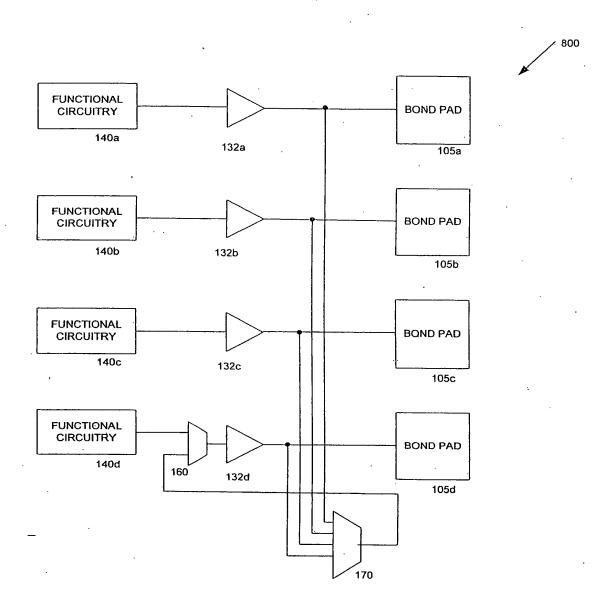


FIG. 8

"Layout and Use of Bond Pads and Probe Pads for Testing of Integrated Circuits Devices" Inventor: Adrian E. Ong Atty. Docket No.: 24295-81051 Sheet 9 of 9

